Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	. 10	(US-20030032263-\$ or US-20030006795-\$ or US-20020194564-\$ or US-20040195672-\$).did. or (US-6237054-\$ or US-5341096-\$ or US-4728751-\$ or US-6094736-\$ or US-6263422-\$ or US-5673276-\$).did.	US-PGPUB; USPAT	OR	OFF	2007/04/01 17:43
L2	3	1 and (DUT device adj2 test)	US-PGPUB; USPAT	OR	OFF	2007/04/01 17:46
L3	3	1 and under with test\$3	US-PGPUB; USPAT	OR	ON	2007/04/01 17:52
L4	. 7	1 and device with test\$3	US-PGPUB; USPAT	OR	ON	2007/04/01 17:52
L5	4755	(internal or boundary) scan	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2007/04/01 18:04
L6	1	(US-20040195672-\$).did.	US-PGPUB	OR	OFF	2007/04/01 18:04
L7	1	L5 and L6	US-PGPUB; USPAT	OR	OFF	2007/04/01 18:04
L8	223	internal scan same boundary scan	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2007/04/01 18:04
L9	1	L8 and L6	US-PGPUB; USPAT	OR	OFF	2007/04/01 18:04
L10	24007	internal circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2007/04/01 18:04

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L12	16	(US-20020194564-\$ or US-20030006795-\$ or US-20030032263-\$ or US-20040195672-\$ or US-20040197941-\$ or US-20040199840-\$ or US-20040221143-\$).did. or (US-6094736-\$ or US-4728751-\$ or US-5673276-\$ or US-6263422-\$ or US-6237054-\$ or US-6330666-\$ or US-5383192-\$ or US-5341096-\$ or US-6734549-\$).did.	US-PGPUB; USPAT	OR	OFF	2007/04/01 18:04
L13	22	(silicon semiconductor) same ceramic same (submount mount) same (TCE thermal adj coefficient)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/04/01 18:07
L14	138	boundary scan and scan chain and IP	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2007/04/01 18:07
L15	1818	(multi-chip package or MCP or multi-chip module or MCM) near3 (semiconductor or silicon)	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/04/01 18:07
L16	27	boundary scan and L15	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/04/01 18:07
L17	12	scan chain and L15	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/04/01 18:07
L18	6	L16 and L17	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/04/01 18:07
L19	55	chip adj IP and IP and intellectual adj property	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/04/01 18:07
L20	103	L14 and (silicon semiconductor gaas inp)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/04/01 18:07
L21	21	IP Super-Sub	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	ADJ	ON	2007/04/01 18:07

L22	82	chip adj IP and IP	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR .	ON	2007/04/01 18:07
L23	53	interface with two-wire adj type	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/04/01 18:07
L24	1230	boundary scan test	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/04/01 18:07
L25	23	L24 and internal scan chain	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/04/01 18:07
L26	19	L25 and (board pcb mount mounting substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/01 18:07
L27	12	L26 and (wire wiring bond bonding)	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/01 18:07
L28	9	L27 and input terminal and output terminal	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/04/01 18:07
L29	147	L24 and internal scan	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2007/04/01 18:07
L30	132	L29 and (board pcb mount mounting substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/01 18:07
L31	102	L30 and (wire wiring bond bonding)	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/01 18:07

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L32	6	(("20020194564") or ("6519728") or ("6400173") or ("20020171449") or ("20030006795") or ("20030032263")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/01 18:07
L33	3192	(714/724,726,727).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/01 18:07
L34	353	L24 and L33	US-PGPUB; USPAT; USOCR	ADJ	OFF	2007/04/01 18:07
L35	42	L23 and (test tested testing tester test adj frame)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR .	ON	2007/04/01 18:07
L36	85	L31 and chip	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/01 18:07
L37	103	L20 and (test tested testing tester test adj frame)	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	ON	2007/04/01 18:07
L38	12	L27 and input and output	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/01 18:07
L39	1273	(257/48).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/04/01 18:07